

300mm Fully-Automatic BG Tape Laminator

RAD-3510F/12



Outline

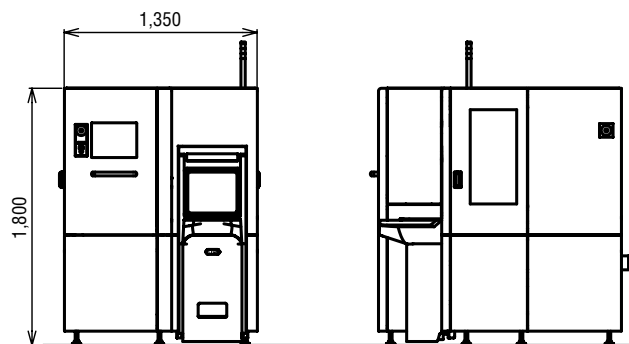
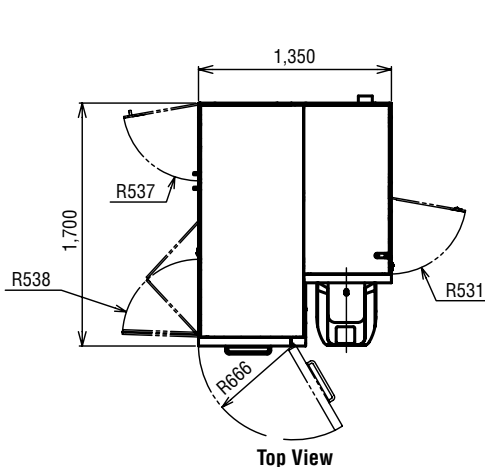
–High precision fully-automatic BG Tape laminator. Wafer handling with non-contact alignment, tape lamination by TTC* technology and tape cutting with a multi-joint robot mechanism.

*TTC (Tape Tension Control) System : The TTC is a cutting-edge system, in which a microcomputer controls tape tension. It enables the tape to be laminated according to the tape type and back-end processing conditions. On the fully-automatic type, tape application torque and torque curve can be set and registered with the equipment's touch screen.

- Options**
- Host Communication Function (Communication Format : Conforms to SECS-I and HSMS/Software : Conforms to GEM)
 - Double Cassette Loading
 - Wafer Box Loading
 - Wafer ID Reader
 - RFID Traceability System

Suitable Tapes ·BG Tape : Adwill E series, P series

External View



Unit:mm

Facility

Power Supply	Voltage	: AC200-230V ±10% (AC190-253V)
	Frequency	: 50/60Hz
	Phase	: single phase
Air Supply	Power consumption	: 1.0kW
	Air pressure	: 0.5-0.8MPa
	Air consumption	: >150L/min (ANR)
Vacuum Supply	Vacuum pressure	: >-80kPa

Applicable Wafer Size

200mm, 300mm

Please inquire about options for compatibility with specific wafer sizes.

Size

Width : 1,350mm
Depth : 1,700mm
Height : 1,800mm
(excluding the signal tower)

Weight

1,500kg

UPH

60wafers/hour

The above processing capacity is based on following conditions:

Wafer : 300mm diameter non-polished mirror wafer
Back grinding tape : P-1600B from LINTEC



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